

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	10/09'15	Yang		WEI

Specification

* Electrical Characteristics :

Current Rating: 0.5A AC/DC Max.

Dielectric Withstanding Voltage: 250V AC/DC

Insulation Resistance: 500M ohms Min.

Contact Resistance: 100m ohms Max.

* Mechanical Characteristics:

Mating Cycles: 5000 Insertions.

* Environmental :

Operating Temperature: -40°C to +85°C.

* Material:

1.Housing: HI-Temp plastic UL 94V-0 Rated.

2.Contact: Copper Alloy.

3.Shell: Stainless Steel SUS 301, t=0.20mm.

* Plating :

Terminal:

Contact area: G/F Plated Over 30u" Nickel.

Solder area: 80u" Tin Plated Over 30u" Nickel.

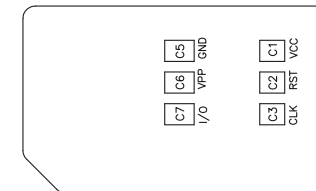
Under plate: 30u"Min. Nickel.

Shell:

30u"Min. Nickel Plated Over All,

Solder Area: Gold Flash.

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	CD SW LOWER
P8#	CD SW UPPER

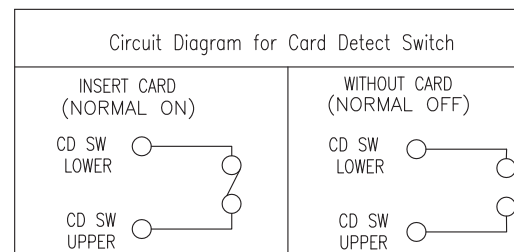


SIM 示意图

芯片面朝下视图

RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES: ±0.05
SOLDER AREA

SECTION A-A



MILLIMETERS	INCH
X° ± 2'	X° ± 2'
.X ± 0.30	.XX ± 0.012
.XX ± 0.20	.XXX ± 0.008
.XXX ± 0.10	.XXXX ± 0.004

UNITS	MM
MAT'L	
SEE NOTES	
FINISH	
SEE NOTES	
QTY	
SEE NOTES	

东莞市涪程电子科技有限公司			
PART NUMBER: 102011022		TITLE: SIM card 6+2 pin push H2.2	
APPD: WEI		DWG NO.: C-102011022-00	
CHKD:			
DR: Yang			
SCALE 1:1	SHEET 1/2	REV. A0	

